

TinyLogic UHS Dual 2-Input NAND Gate

NC7WZ00

Description

The NC7WZ00 is a dual 2–Input NAND Gate from **onsemi**'s Ultra High Speed Series of TinyLogic. The device is fabricated with advanced CMOS technology to achieve ultra high speed with high output drive while maintaining low static power dissipation over a broad V_{CC} operating range. The device is specified to operate over the 1.65 V to 5.5 V V_{CC} operating range. The inputs and output are high impedance when V_{CC} is 0 V. Inputs tolerate voltages up to 5.5 V independent of V_{CC} operating voltage.

Features

- Space Saving US8 Surface Mount Package
- MicroPakTM Leadless Package
- Ultra High Speed: t_{PD} 2.4 ns Typ. into 50 pF at 5 V V_{CC}
- High Output Drive: ±24 mA at 3 V V_{CC}
- Broad V_{CC} Operating Range: 1.65 V 5.5 V
- Matches the Performance of LCX when Operated at 3.3 V V_{CC}
- Power Down High Impedance Inputs / Output
- Overvoltage Tolerant Inputs Facilitate 5 V to 3 V Translation
- Proprietary Noise / EMI Reduction Circuitry Implemented
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

MARKING DIAGRAMS



UQFN8 1.6X1.6, 0.5P CASE 523AY





US8 CASE 846AN



N6, WZ00 = Specific Device Code

KK = 2-Digit Lot Run Traceability Code
XY = 2-Digit Date Code Format
Z = Assembly Plant Code
A = Assembly Site
L = Wafer Lot Number
YW = Assembly Start Week

ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 6 of this data sheet.

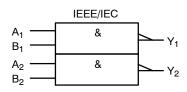


Figure 1. Logic Symbol

1

Pin Configurations

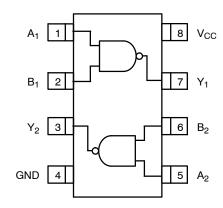
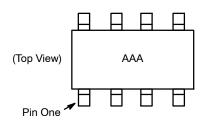


Figure 2. Connection Diagram (Top View)



AAA represents Product Code Top Mark - see ordering code

NOTE: Orientation of Top Mark determines Pin One location. Read the top product code mark left to right, Pin One is the lower left pin (see diagram).

Figure 3. Pin One Orientation Diagram

PIN DESCRIPTION

Pin Names	Description
A _n , B _n	Inputs
Y _n	Output

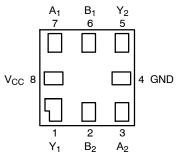


Figure 4. Pad Assignments for MicroPak (Top Thru View)

FUNCTION TABLE $(Y = \overline{AB})$

Inp	Output	
Α	В	Υ
L	L	Н
L	Н	Н
Н	L	Н
Н	Н	L

H = HIGH Logic Level L = LOW Logic Level

NC7WZ00

ABSOLUTE MAXIMUM RATINGS

Symbol	Parame	Min	Max	Unit	
V _{CC}	Supply Voltage	Supply Voltage			V
V _{IN}	DC Input Voltage		-0.5	6.5	V
V _{OUT}	DC Output Voltage		-0.5	6.5	V
I _{IK}	DC Input Diode Current	V _{IN} < 0 V	-	-50	mA
I _{OK}	DC Output Diode Current	V _{OUT} < 0 V	-	-50	mA
I _{OUT}	DC Output Current	-	±50	mA	
I _{CC} / I _{GND}	DC V _{CC} / GND Current	-	±100	mA	
T _{STG}	Storage Temperature		-65	+150	°C
TJ	Junction Temperature Under Bias		-	150	°C
TL	Junction Lead Temperature (Solde	-	260	°C	
P _D	Power Dissipation in Still Air	US8 MicroPak-8	- -	500 539	mW

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

RECOMMENDED OPERATING CONDITIONS

Symbol		Parameter	Min	Max	Unit
V _{CC}	Supply Voltage Operating		1.65	5.5	V
	Supply Voltage Data Rete	ntion	1.5	5.5	
V _{IN}	Input Voltage		0	5.5	V
V _{OUT}	Output Voltage		0	V _{CC}	V
T _A	Operating Temperature		-40	+85	°C
t _r , t _f	Input Rise and Fall Time		0	20	ns/V
	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$ $V_{CC} = 5.0 \text{ V} \pm 0.5 \text{ V}$		0	10	
			0	5	
$\theta_{\sf JA}$	Thermal Resistance	US8 MicroPak-8	- -	250 232	°C/W

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

1. Unused inputs must be held HIGH or LOW. They may not float.

NC7WZ00

DC ELECTICAL CHARACTERISTICS

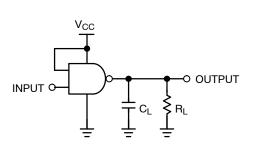
						T _A = +25°C			to +85°C	
Symbol	Parameter	V _{CC} (V)	Conditions		Min	Тур	Max	Min	Max	Unit
V _{IH}	HIGH Level Input	1.65 – 1.95			0.65 V _{CC}	-	-	0.65 V _{CC}	_	V
	Voltage	2.3 – 5.5	1		0.70 V _{CC}	-	-	0.70 V _{CC}	_	
V_{IL}	LOW Level Input	1.65 – 1.95			-	-	0.35 V _{CC}	-	0.35 V _{CC}	V
	Voltage	2.3 – 5.5			-	-	0.30 V _{CC}	_	0.30 V _{CC}	
V _{OH}	HIGH Level Output	1.65	$V_{IN} = V_{IL}$	$I_{OH} = -100 \mu A$	1.55	1.65	-	1.55	_	٧
	Voltage	2.3	1		2.2	2.3	-	2.2	_	
		3.0	1		2.9	3.0	-	2.9	_	
		4.5	1		4.4	4.5	-	4.4	_	
		1.65		$I_{OH} = -4 \text{ mA}$	1.29	1.52	-	1.69	_	1
		2.3	1	I _{OH} = -8 mA	1.9	2.15	-	1.9	_	
		3.0	1	I _{OH} = -16 mA	2.4	2.80	-	2.4	_	
		3.0	1	I _{OH} = -24 mA	2.3	2.68	-	2.3	_	
		4.5	1	I _{OH} = -32 mA	3.8	4.20	-	3.8	_	
V_{OL}	LOW Level Output	1.65	$V_{IN} = V_{IH}$	I _{OL} = 100 μA	-	0.0	0.1	_	0.1	V
	Voltage	2.3			-	0.0	0.1	_	0.1	
		3.0			-	0.0	0.1	_	0.1	
		4.5			-	0.0	0.1	_	0.1	
		1.65		I _{OL} = 4 mA	-	0.08	0.24	_	0.24	
		2.3	1	I _{OL} = 8 mA	-	0.10	0.3	_	0.3	
		3.0	1	I _{OL} = 16 mA	-	0.15	0.4	_	0.4	
		3.0		I _{OL} = 24 mA	_	0.22	0.55	_	0.55	
		4.5	1	I _{OL} = 32 mA	-	0.22	0.55	_	0.55	
I _{IN}	Input Leakage Current	1.65 – 5.5	V _{IN} = 5.5 V, GND			_	±0.1	_	±1	μΑ
I _{OFF}	Power Off Leakage Current	0.0	V _{IN} or V _{OUT} = 5.5 V		-	-	1	-	10	μΑ
I _{CC}	Quiescent Supply Current	1.65 – 5.5	V _{IN} = 5.5 \	/, GND	-	-	1	-	10	μΑ

AC ELECTRICAL CHARACTERISTICS

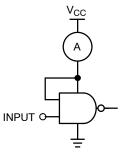
				T _A = +25°C		T _A = -40	to +85°C		
Symbol	Parameter	V _{CC} (V)	Conditions	Min	Тур	Max	Min	Max	Unit
t _{PLH} , t _{PHL}	Propagation Delay	1.8 ±0.15	C _L = 15 pF,	-	5.3	9.6	-	9.8	ns
	(Figure 5, 7)	2.5 ±0.2	$R_L = 1 M\Omega$,	-	3.2	5.3	-	5.7	
		3.3 ±0.3		_	2.4	3.7	_	4.0	
		5.0 ±0.5		_	1.9	2.9	_	3.2	
		3.3 ±0.3	C _L = 50 pF,	_	3.0	4.6	-	4.9	
		5.0 ±0.5	$R_L = 500 \Omega$,	-	2.4	3.6	-	3.9	
C _{IN}	Input Capacitance	0		-	2.5	-	-	-	pF
	Power Dissipation Capacitance	3.3	(Note 2)	-	13	-	-	-	pF
	(Figure 6)	5.0		_	17	-	-	-	

^{2.} C_{PD} is defined as the value of the internal equivalent capacitance which is derived from dynamic operating current consumption (I_{CCD}) at no output loading and operating at 50% duty cycle. (see Figure 6) C_{PD} is related to I_{CCD} dynamic operating current by the expression: I_{CCD} = (C_{PD}) (V_{CC}) (f_{IN}) + (I_{CC}static).

AC Loading and Waveforms



 C_L includes load and stray capacitance Input PRR = 1.0 MHz, t_W = 500 ns



Input = AC Waveform; $t_r = t_f = 1.8$ ns; PRR = 10 MHz; Duty Cycle = 50%.

Figure 5. AC Test Circuit

Figure 6. I_{CCD} Test Circuit

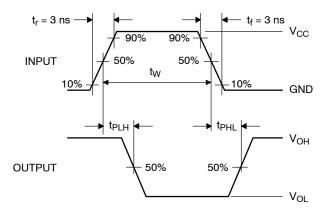


Figure 7. AC Waveforms

NC7WZ00

ORDERING INFORMATION

Order Number	Top Mark	Package	Shipping [†]
NC7WZ00K8X	WZ00	8-Lead US8, JEDEC MO-187, Variation CA 3.1 mm Wide	3000 / Tape & Reel
NC7WZ00K8X-L22236	WZ00	8-Lead US8, JEDEC MO-187, Variation CA 3.1 mm Wide	3000 / Tape & Reel
NC7WZ00L8X	N6	8-Lead MicroPak, 1.6 mm Wide	5000 / Tape & Reel

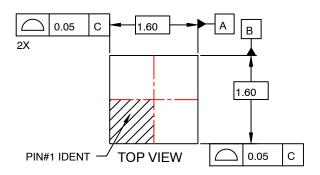
[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

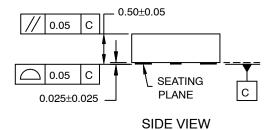
3. All packages are lead free per JEDEC: J-STD-020B standard.

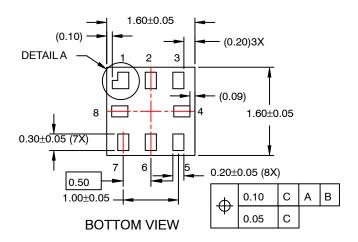
MicroPak is trademark of Semiconductor Components Industries, LLC (SCILLC) or its subsidiaries in the United States and/or other countries.

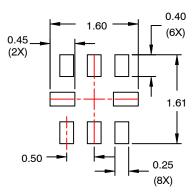
UQFN8 1.6X1.6, 0.5P CASE 523AY ISSUE O

DATE 31 AUG 2016





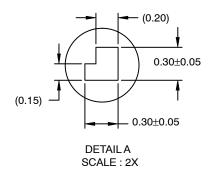




RECOMMENDED LAND PATTERN

NOTES:

- A. PACKAGE CONFORMS TO JEDEC MO-255 VARIATION UAAD.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009.
- D. LAND PATTERN RECOMMENDATION IS EXISTING INDUSTRY LAND PATTERN.

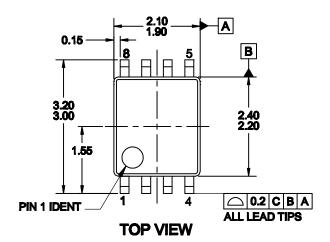


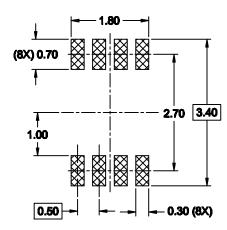
DOCUMENT NUMBER:	98AON13591G	Electronic versions are uncontrolled except when accessed directly from the Document Reposi Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.			
DESCRIPTION:	UQFN8 1.6X1.6, 0.5P		PAGE 1 OF 1		

ON Semiconductor and a re trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

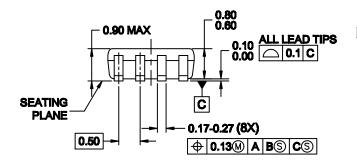
US8 CASE 846AN ISSUE O

DATE 31 DEC 2016





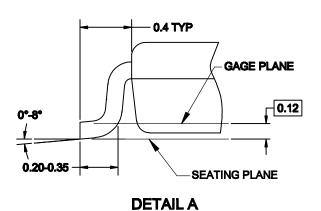
RECOMMENDED LAND PATTERN

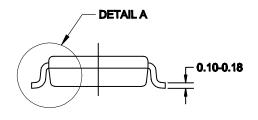


NOTES:

- A. CONFORMS TO JEDEC REGISTRATION MO-187
- **B. DIMENSIONS ARE IN MILLIMETERS.**
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1994.

SIDE VIEW





DOCUMENT NUMBER:	98AON13778G	Electronic versions are uncontrolled except when accessed directly from the Document Rep Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.			
DESCRIPTION:	US8		PAGE 1 OF 1		

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

onsemi, ONSEMi., and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. Onsemi reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using onsemi products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications provided by onsemi. "Typical" parameters which may be provided in onsemi data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. onsemi does not convey any license under any of its intellectual property rights nor the rights of others. onsemi products are not designed, intended, or authorized for use as a critical component in life support systems or any EDA class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer p

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT: Email Requests to: orderlit@onsemi.com

onsemi Website: www.onsemi.com

TECHNICAL SUPPORT North American Technical Support: Voice Mail: 1 800-282-9855 Toll Free USA/Canada Phone: 011 421 33 790 2910

Europe, Middle East and Africa Technical Support:

Phone: 00421 33 790 2910

For additional information, please contact your local Sales Representative